| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Drain Source Voltage | $V_{DSS}$ | 500 | V |

## / Electrical Characteristics(Ta=25 )

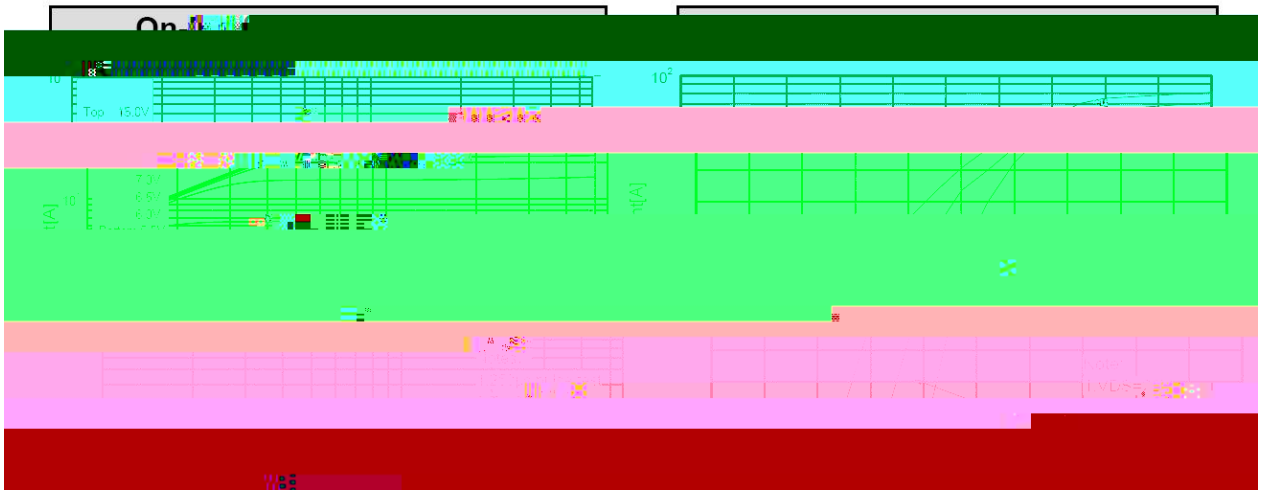
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Drain-Source Breakdown Voltage | $BV_{DSS}$ | $V_{GS}$=0V $I_D$=250μA | 500 | | | V |
| Drain-Source Leakage Current | $I_{DSS}$ | $V_{DS}$=500V $V_{GS}$=0V | | | 1 | μA |
| Gate- Source Leakage Current Forward | $I_{GSSF}$ | $V_{DS}$=0V $V_{GS}$=+30V | | | +100 | nA |
| Gate-Source Leakage Current Reverse | $I_{GSSR}$ | $V_{DS}$=0V $V_{GS}$=-30V | | | -100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$= $V_{GS}$ $I_D$=250μA | 3.0 | | 5.0 | V |
| Static Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}$ =10V $I_D$=13A | | 0.17 | 0.2 | Ω |
| Input Capacitance | $C_{iss}$ | $V_{DS}$=25V $V_{GS}$ =0V, f=1.0MHZ | | 3360 | | pF |
| Output Capacitance | $C_{oss}$ | | | 280 | | |
| Reverse Transfer Capacitance | $C_{rss}$ | | | 35 | | |
| Total Gate Charge | | $V_{GS}$=10V $V_{DS}$=400V $I_D$=26A (Note 1, 2) | | 81 | 120 | nC |
| Gate to Source Charge | | | | 23 | | |
| Gate to Drain Charge | | | | 35 | | |
| | $t_{D(ON)}$ | $V_{DD}$=250V $I_D$=26A $R_G$=25Ω (Note 1, 2) | | 80 | 170 | ns |
| Rise Time | $t_R$ | | | 2500 | 500 | |
| Turn-OFF Delay Time | $t_{D(OFF)}$ | | | 200 | 400 | |
| Fall-Time | $t_F$ | | | 155 | 320 | |
| Maximum Body-Diode Continuous Current | $I_S$ | | | | 26 | A |
| Maximum Body-Diode Pulsed Current | $I_{SM}$ | | | | 104 | A |
| Drain-Source Diode Forward Voltage | $V_{SD}$ | $I_S$=26A $V_{GS}$=0V | | | 1.4 | V |
| Body Diode Reverse Recovery Time | $T_{rr}$ | $I_S$=26A $V_{GS}$=0V dIF/dt=100A/μs (Note 1) | | 530 | | ns |
| Body Diode Reverse Recovery Charge | $Q_{RR}$ | | | 8.2 | | μC |

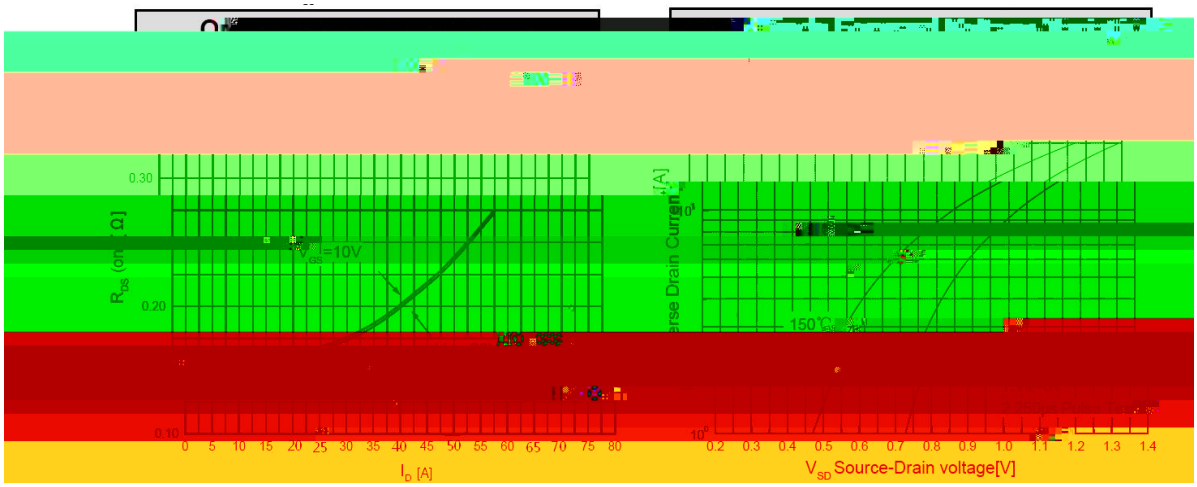
1. ≤300μs ≤2%
2.

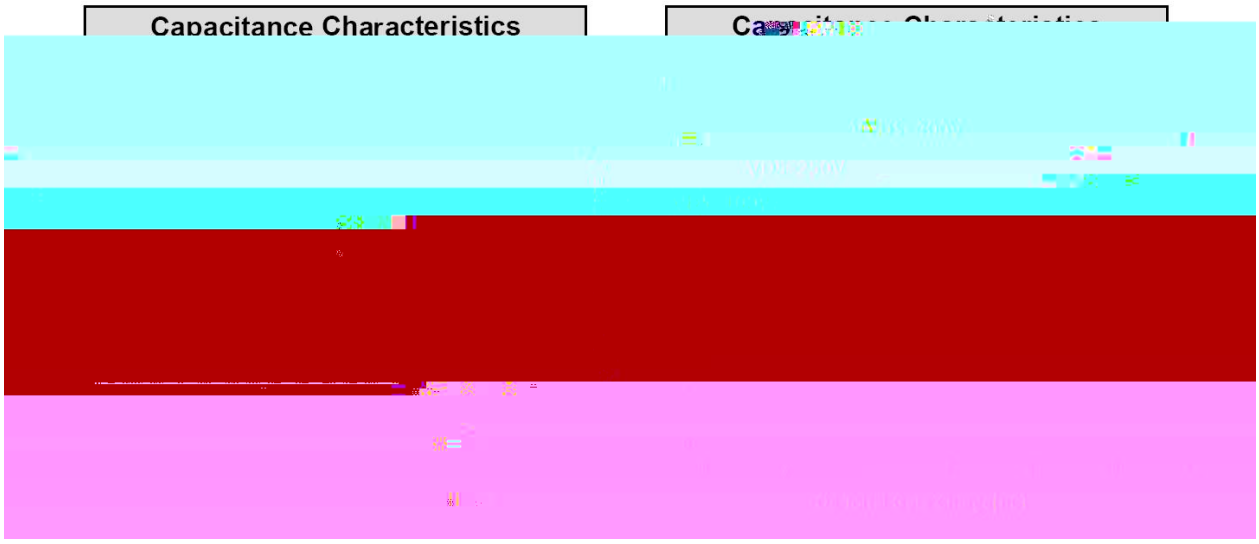
ote:

1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating temperature.

## / Electrical Characteristic Curve

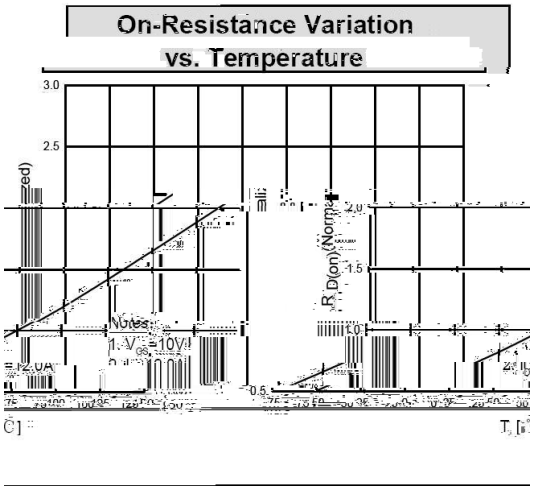


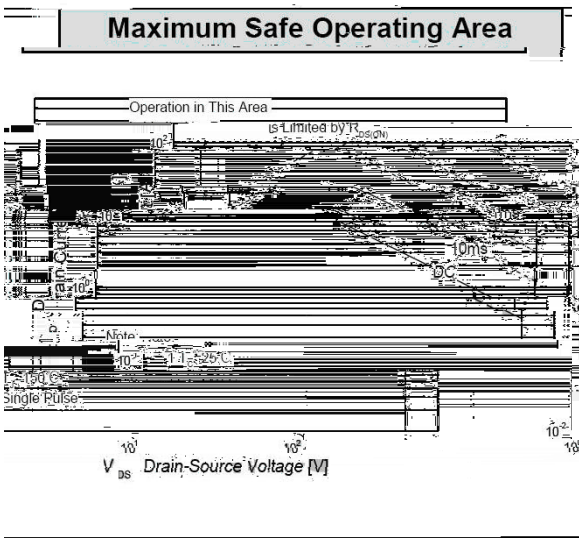


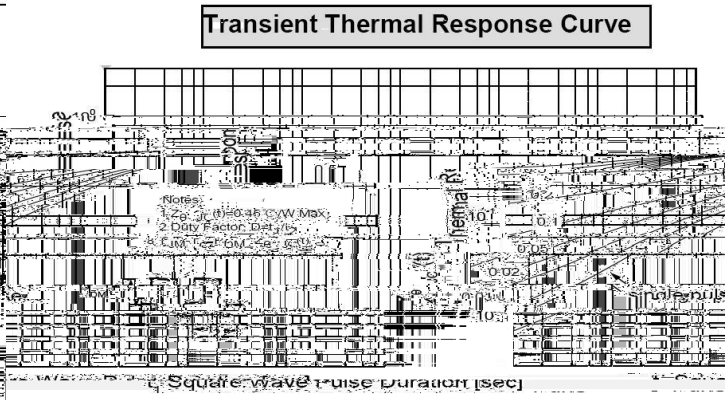



## / Electrical Characteristics(Ta=25 )

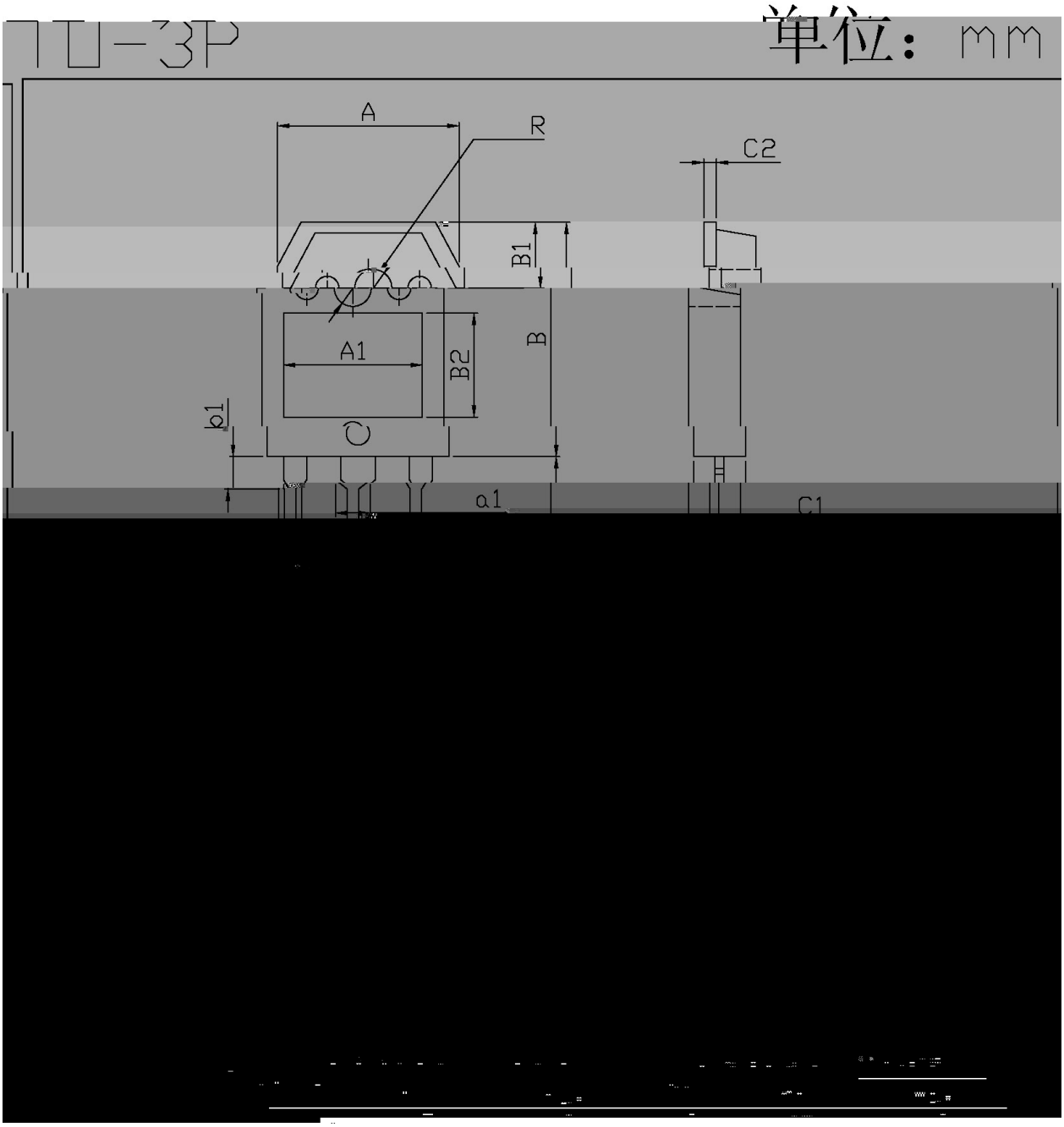


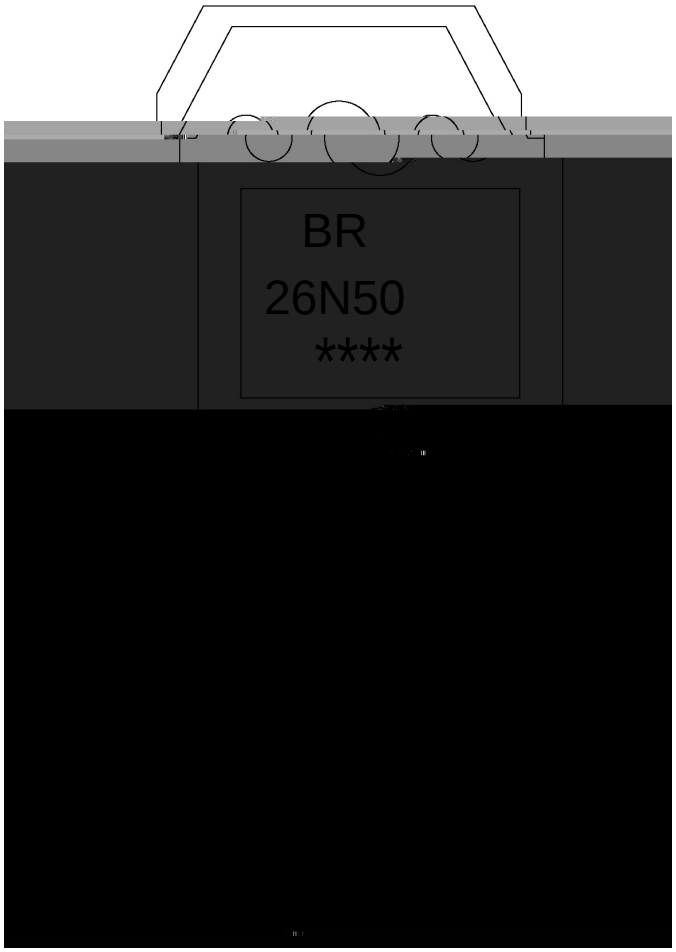



## / Package Dimensions



## / Marking Instructions




BR:

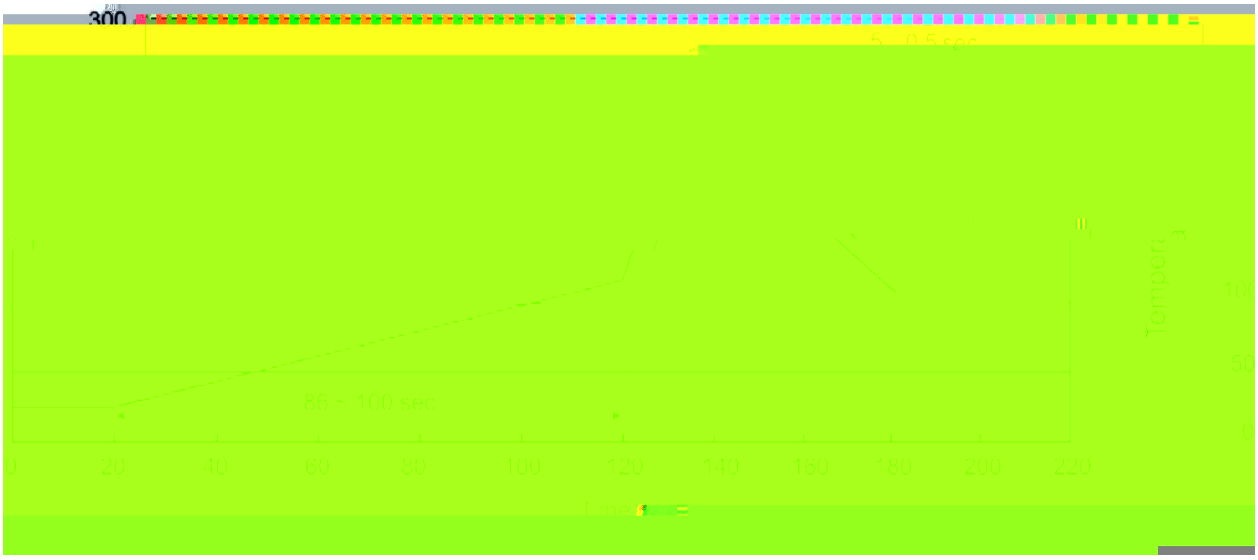
26N50

****

Note:

| | |
|---|---|
| BR: | Company Code. |
| 26N50: | Product Type. |
| ****: | Lot No. Code, code change with Lot No. |

## ( ) / Temperature Profile for Dip Soldering(Pb-Free)




| | | | | | |
|---|---|---|---|---|---|
| | | | | | Note: |
| 1 | | 25 | 150 | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| 270±5 | 10±1 sec. | Temp:270±5 | Time:10±1 sec |

## / Packaging SPEC.

### / TUBE

| Package Type 封装形式 | Units 已装数量 | | | | | Dimension 已装尺寸 (unit: $mm^3$) | | |
|---|---|---|---|---|---|---|---|---|
| | Units/Tube 只/套管 | Tubes/Inner Box 套管/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Tube 套管 | Inner Box 盒 | Outer Box 箱 |